

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
YU-WEI TING	07/31/2014
CHI-WEN LIU	08/01/2014
CHUN-YANG TSAI	07/31/2014
KUO-CHING HUANG	07/31/2014
RECEIVING PARTY DATA	
Name:	TAIWAN SEMICONDUCTOR MANUFACTURING CO., LTD.
Street Address:	NO. 8, LI-HSIN RD. 6
Internal Address:	HSIN-CHU SCIENCE PARK
City:	HSIN-CHU
State/Country:	TAIWAN
Postal Code:	300-77
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	14450809
CORRESPONDENCE DATA	
Fax Number:	(216)502-0601
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
Phone:	216-502-0600
Email:	docketing@eschweilerlaw.com
Correspondent Name:	ESCHWEILER & ASSOCIATES, LLC.
Address Line 1:	629 EUCLID AVENUE, SUITE 1000
Address Line 2:	NATIONAL CITY BANK BUILDING
Address Line 4:	CLEVELAND, OHIO 44114
ATTORNEY DOCKET NUMBER:	TSMCP196USA
NAME OF SUBMITTER:	THOMAS G. ESCHWEILER
SIGNATURE:	/Thomas G. Eschweiler/
DATE SIGNED:	08/04/2014
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TSMC Docket No. TSMC2012-0729CIP

U.S. Patent Appln. No.

Docket No. TSMCP196USA

Filing Date:

PATENT ASSIGNMENT

PARTIES TO THE ASSIGNMENT

Assignor(s):

Yu-Wei Ting
2F., No.14
Aly. 69, Ln. 66
Wende Rd., Neiñu Dist.
Taipei City 114
Taiwan (R.O.C.)

Assignor(s):

Chi-Wen Liu
3F, No. 561, Nan-Da Rd.
Hsinchu
Taiwan (R.O.C.)

Assignor(s):

Chun-Yang Tsai
No.19-6, Houhu
Hubei Vil., Linkou Dist.
New Taipei City 244
Taiwan (R.O.C.)

Assignor(s):

Kuo-Ching Huang
6F.-1, No.419-3, Sec 2
Gongdao 5th Rd., East Dist.
Hsinchu City 300
Taiwan (R.O.C.)

Assignee:

Taiwan Semiconductor Manufacturing Co., Ltd.
No. 8, Li-Hsin Rd. 6, Hsin-Chu Science Park
Hsin-Chu, Taiwan 300-77
Republic of China

AGREEMENT

WHEREAS, ASSIGNOR(S) (listed above) are inventor(s) of an invention entitled
**"AN INNOVATIVE APPROACH OF 4F² DRIVER FORMATION
FOR HIGH-DENSITY RRAM AND MRAM"** for which:

a non-provisional application for United States Letters Patent:

U.S. Patent Appln. No.

Docket No. TSMCP196USA

Filing Date:

was executed on even date preparatory to filing (each inventor should sign this Assignment on the same day as he/she signs the Declaration and Power of Attorney); or

was filed on _____ and accorded U.S. Serial No. _____; or

will be filed without this executed PATENT ASSIGNMENT. ASSIGNOR hereby authorizes and requests ASSIGNEE'S legal representatives, the attorneys associated with Customer No. _____, to insert below in this document this APPLICATION's U.S. Serial Number and filing date, when known:

U.S. Serial No. _____,

filed on _____.

WHEREAS, ASSIGNEE (listed above), a corporation of the Republic of China is desirous of acquiring the entire right, title and interest in and to the invention and in and to any letters patent that may be granted therefore in the United States and in any and all foreign countries;

NOW, THEREFORE, in exchange for good and valuable consideration, the receipt of which is hereby acknowledged, ASSIGNOR(S) hereby sell, assign and transfer unto ASSIGNEE its successors and assigns, the entire right, title and interest in and to said invention and improvements, said application and any and all letters patent which may be granted for said invention in the United States of America and its territorial possessions and in any and all foreign countries, and in any and all divisions, reissues, re-examinations and continuations thereof, including the right to file foreign applications directly in the name of ASSIGNEE and to claim priority rights deriving from said United States application to which said foreign applications are entitled by virtue of international convention, treaty or otherwise, said invention, application and all letters patent on said invention to be held and enjoyed by

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ASSIGNEE and its successors and assigns for their use and benefit and of their successors and assigns as fully and entirely as the same would have been held and enjoyed by ASSIGNOR(S) had this assignment, transfer and sale not been made. ASSIGNOR(S) hereby authorize and request the Commissioner of Patents and Trademarks to issue all letters patent on said invention to ASSIGNEE. ASSIGNOR(S) agree to execute all instruments and documents required for the making and prosecution of applications for United States and foreign letters patent on said invention, for litigation regarding said letters patent, or for the purpose of protecting title to said invention or letters patent therefore.

✓ 2014.07.31
Date

✓ 丁裕婷
Name 1st Inventor Yu-Wei Ting

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Filing Date:

✓ 08/01/2014
Date

✓ 廖文文
Name 2nd Inventor Chi-Wen Liu

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Filing Date:

✓ 2014/07/31
Date

TSMC Docket No. TSMC2012-0729CIP

Docket No. TSMCP196USA

✓ 蔡政揚
Name 3rd Inventor Chun-Yang Tsai

TSMC Docket No. TSMC2012-0729CIP

Docket No. TSMCP196USA

U.S. Patent Appln. No.

Filing Date:

✓ 2014/01/31
Date

✓ 
Name 4th Inventor Kuo-Ching Huang